Vishay Siliconix



P-Channel 80 V (D-S) MOSFET



Marking Code: BU

PRODUCT SUMMARY						
V _{DS} (V)	-80					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10 \text{ V}$	0.0827					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.1242					
Q _g typ. (nC)	5.6					
I _D (A) ^a	-5.4					
Configuration	Single					

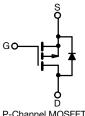
FEATURES

- TrenchFET® power MOSFET
- 100 % R_g tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Power management for portable and consumer
 - Load switches
 - DC/DC converters



P-Channel MOSFET

ORDERING INFORMATION	
Package	TSOP-6 Single
Lead (Pb)-free and halogen-free	Si3129DV-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-80	V	
Gate-source voltage		V _{GS}	±20	v	
	T _C = 25 °C		-5.4		
Opation and design and (T. 150 °C)	T _C = 70 °C		-4.4		
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	-3.8 b, c		
	T _A = 70 °C		-3.0 b, c		
Pulsed drain current (t = 300 μs)	I _{DM}	-20	А		
	T _C = 25 °C		-3.5		
Continuous source-drain diode current	T _A = 25 °C	I _S	-1.7 ^{b, c}		
Single pulse avalanche energy	. 0411	I _{AS}	15		
	L = 0.1 mH	E _{AS}	11		
Maximum power dissipation	T _C = 25 °C		4.2		
	T _C = 70 °C		2.7	14/	
	T _A = 25 °C	P _D	2 b, c	W	
	T _A = 70 °C		1.3 ^{b, c}		
Operating junction and storage temperature ra	T _{.I} , T _{sta}	-55 to 150	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient b, d	t ≤ 5 s	R _{thJA}	45	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	Rth.IF	25	30	C/VV	

Notes

- a. $T_C = 25 \,^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- d. Maximum under steady state conditions is 110 °C/W



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-80	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = -10 mA	-	-115	-	>//90	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	4.8	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1.5	-	-2.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
		V _{DS} = -80 V, V _{GS} = 0 V	-	-	-10		
Zero gate voltage drain current	I _{DSS}	V _{DS} = -80 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-50	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	-5	-	-	Α	
Dunin	0	$V_{GS} = -10 \text{ V}, I_D = -3.8 \text{ A}$	-	0.0689	0.0827	1 _	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -3.1 \text{ A}$	-	0.0994	0.1242	Ω	
Dynamic ^b				•			
Input capacitance	C _{iss}		-	805	-	pF	
Output capacitance	Coss	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	265	-		
Reverse transfer capacitance	C _{rss}		-	10	-		
Total gate charge	Qg	$V_{DS} = -40 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -3.8 \text{ A}$	-	12	18	nC	
			-	5.6	8.4		
Gate-source charge	Q _{gs}	$V_{DS} = -40 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3.8 \text{ A}$	-	3.1	-		
Gate-drain charge	Q_{gd}		-	1.4	-		
Gate resistance	R_g	f = 1 MHz	0.8	4.4	8.8	Ω	
Turn-on delay time	t _{d(on)}		-	15	30		
Rise time	t _r	$V_{DD} = -40 \text{ V}, R_{L} = 13.3 \Omega$	-	8	16	1	
Turn-off delay time	t _{d(off)}	$I_D \cong -3 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	25	50		
Fall time	t _f		-	12	24		
Turn-on delay time	t _{d(on)}		-	28	56	ns	
Rise time	t _r	$V_{DD} = -40 \text{ V}, R_{L} = 13.3 \Omega$	-	42	84		
Turn-off delay time	t _{d(off)}	$I_D \cong -3$ A, $V_{GEN} = -4.5$, $R_g = 1$ Ω	-	24	48		
Fall time	t _f		-	15	30		
Drain-Source Body Diode Characterist	ics						
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	-3.5		
Pulse diode forward current	I _{SM}		-	-	-20	Α	
Body diode voltage	V _{SD}	$I_{S} = -3 \text{ A}, V_{GS} = 0 \text{ V}$	-	-0.8	-1.2	٧	
Body diode reverse recovery time	t _{rr}		-	38	57	ns	
Body diode reverse recovery charge	Q _{rr}	O A 31/31 400 A/ T 57 30	-	50	75	nC	
Reverse recovery fall time	ta	$I_F = -3 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$	-	26	-		
Reverse recovery rise time	t _b		-	12	-	ns	

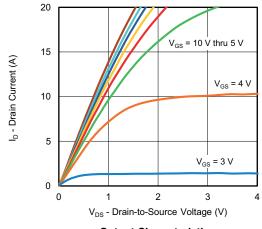
Notes

- a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

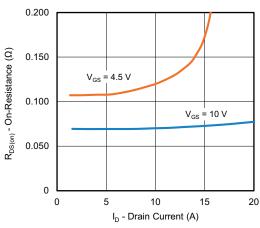
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



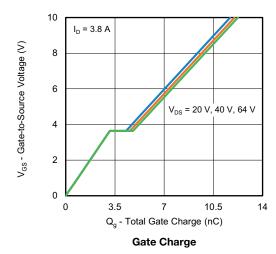
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

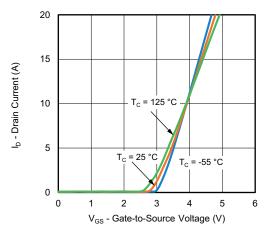


Output Characteristics

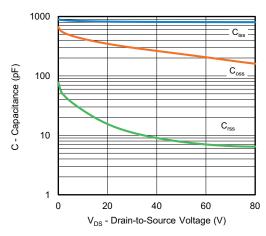


On-Resistance vs. Drain Current

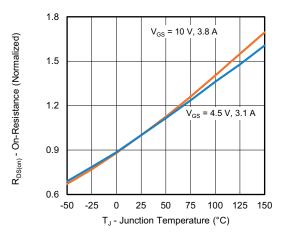




Transfer Characteristics



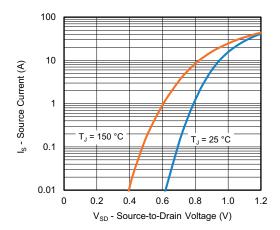
Capacitance



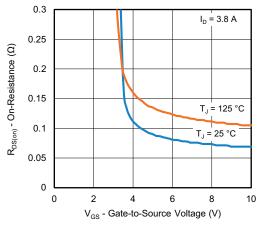
On-Resistance vs. Junction Temperature



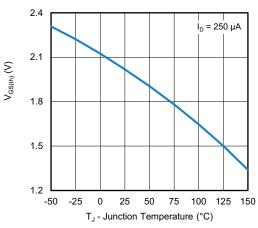
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



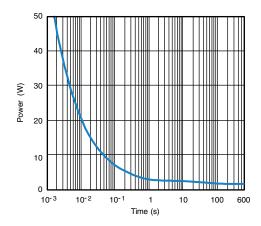
Source-Drain Diode Forward Voltage



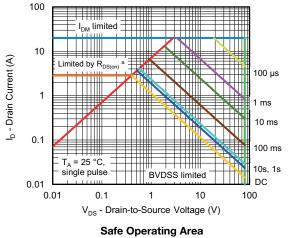
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient



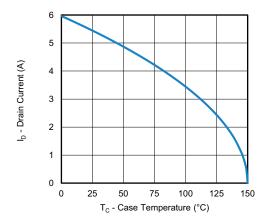
Safe Operating

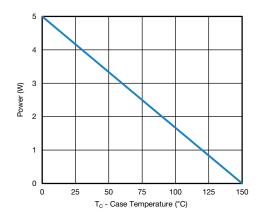
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Note



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Current Derating ^a

Power Junction-to-Case

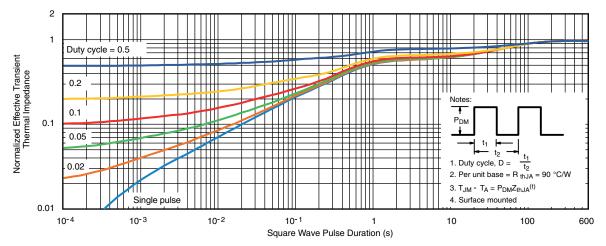
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

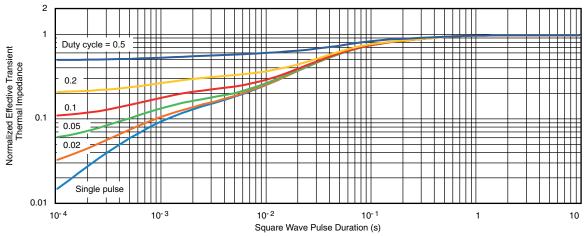


S20-0813-Rev. A, 19-Oct-2020

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

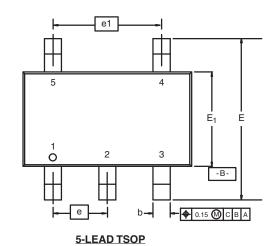
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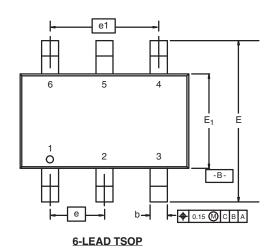




TSOP: 5/6-LEAD

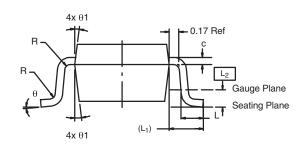
JEDEC Part Number: MO-193C





-A-D · A_2 Seating Plane **a** 0.08 C

-C- A₁

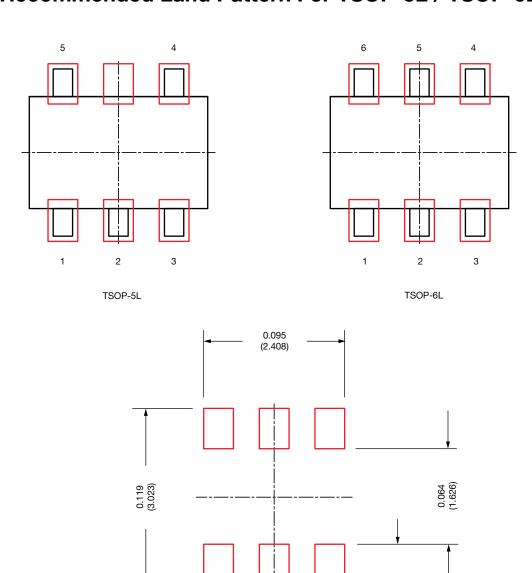


	MILLIMETERS			INCHES				
Dim	Min	Nom	Max	Min	Nom	Max		
Α	0.91	-	1.10	0.036	-	0.043		
A ₁	0.01	-	0.10	0.0004	-	0.004		
A ₂	0.90	-	1.00	0.035	0.038	0.039		
b	0.30	0.32	0.45	0.012	0.013	0.018		
С	0.10	0.15	0.20	0.004	0.006	0.008		
D	2.95	3.05	3.10	0.116	0.120	0.122		
Е	2.70	2.85	2.98	0.106	0.112	0.117		
E ₁	1.55	1.65	1.70	0.061	0.065	0.067		
е		0.95 BSC		0.0374 BSC				
e ₁	1.80	1.90	2.00	0.071	0.075	0.079		
L	0.32	-	0.50	0.012	-	0.020		
L ₁		0.60 Ref			0.024 Ref			
L ₂	0.25 BSC			0.010 BSC				
R	0.10	-	-	0.004	-	-		
θ	0°	4°	8°	0°	4°	8°		
θ_1	7° Nom			7° Nom				
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540								

Document Number: 71200 www.vishay.com 18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: S22-0593-Rev. A, 18-Jul-2022 DWG: 3010

Revision: 18-Jul-2022 1 Document Number: 72610

0.017

(0.442)

0.037 (0.950)

0.020 (0.508)



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